

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1099csw#trpbf

(Engineering Calculation)

SOIC WIDE

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TOTAL MASS (g) : 0.545894

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.007671 | 1000000 | 14052.1855469 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.153163 | 975000 | 280572.90625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003770 | 24000 | 6906.10595703 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000047 | 300 | 86.0973434448 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000110 | 700 | 201.504425049 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.157090 | 1000000 | 287766.59375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.005974 | 1000000 | 10942.9306641 | | |
| | | External Plating Total: | | | | 0.005974 | 1000000 | 10942.9306641 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001257 | 1000000 | 2302.64599609 | | |
| Internal Plating Total: | | | | 0.001257 | 1000000 | 2302.64599609 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001767 | 750000 | 3236.89355469 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000589 | 250000 | 1078.96459961 | | |
| Die Attach Total: | | | | 0.002356 | 1000000 | 4315.85839844 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.038213 | 103000 | 70000.8046875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.332045 | 895000 | 608259.375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000742 | 2000 | 1359.2388916 | | |
| | | Encapsulation Total: | | | | 0.371000 | 1000000 | 679619.4375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000546 | 1000000 | 1000.19470215 | | |
| | | | | | TOTAL MASS (g) : | 0.545894 | | |